

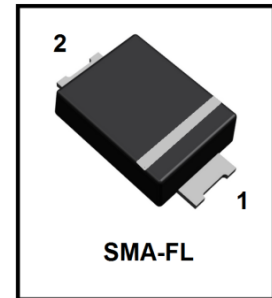
FMAF407

S-FMAF407

Surface Mount Glass Passivated Junction Rectifiers
Reverse Voltage 50 to 1000V Forward Current 1.0A

1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0.
- High temperature metallurgically bonded construction.
- Cavity-free glass passivated junction.
- Typical IR less than 1.0 μ A
- High temperature soldering guaranteed:260°C/10 seconds.
- 1.0 A operation at TL=100°C with no thermal runaway.
- Capable of meeting environmental standards of MIL-S-19500.



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
FMAF407	M07	3000/Tape&Reel
S-FMAF407	S-M07	3000/Tape&Reel

3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Maximum repetitive peak reverse voltage	VRRM	1000	V
Maximum RMS voltage	VRMS	700	V
Maximum DC blocking voltage	VDC	1000	V
Maximum average forward rectified current lead length (See fig. 1) at TC = 75°C	IF(AV)	1	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	30	A
Typical thermal resistance (Note 1)	R θ JA	150	°C/W
Operating junction and storage temperature range	TJ, TSTG	-50 ~+150	°C

4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Maximum instantaneous forward voltage at 1.0A	VF	-	-	1.1	V
Maximum DC reverse current TA = 25°C at rated DC blocking voltage TA = 125°C	IR	-	-	5 50	μ A
Typical junction capacitance at 4.0V, 1MHz	CJ	-	8	-	PF

1. IF = 0.5A, IR = 1.0A, IRR = 0.25A
2. 8.0mm² (.013mm thick) land areas

5. ELECTRICAL CHARACTERISTICS CURVES

Fig. 1 - Forward Current Derating Curve

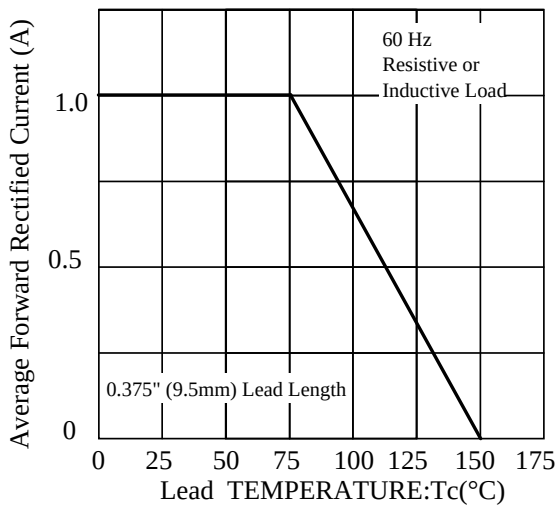


Fig. 2 - Maximum Non-repetitive Peak Forward Surge Current

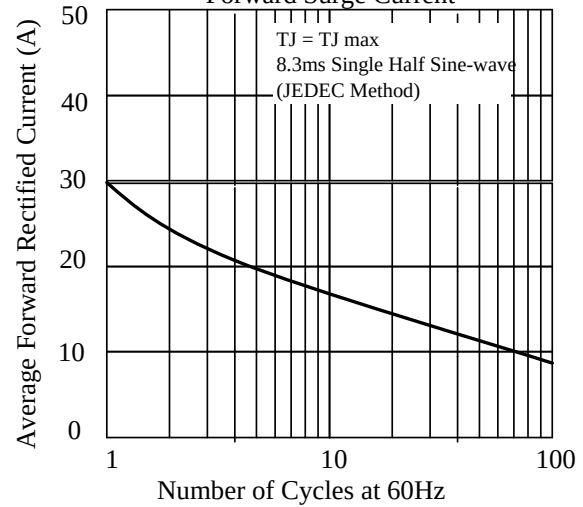


Fig 3. - Typical Instantaneous Forward Characteristics

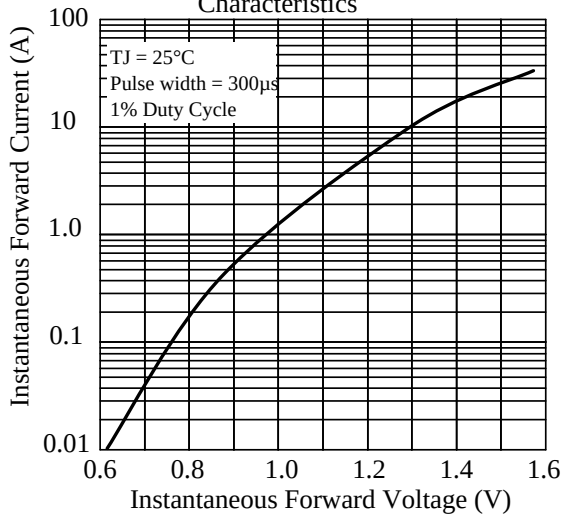


Fig 4. - Typical Reverse Characteristics

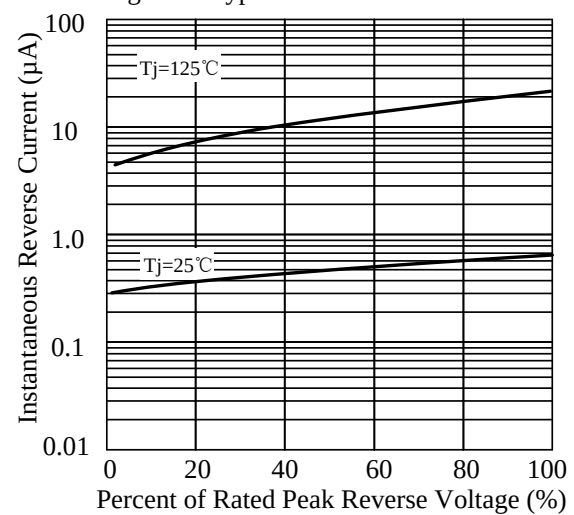


Fig 5. - typical transient thermal impedance

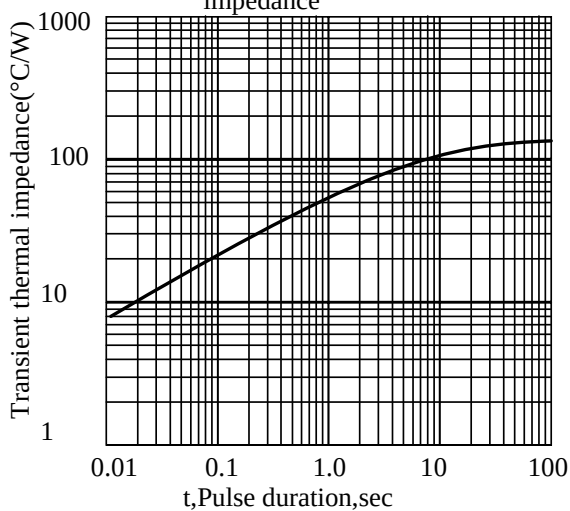
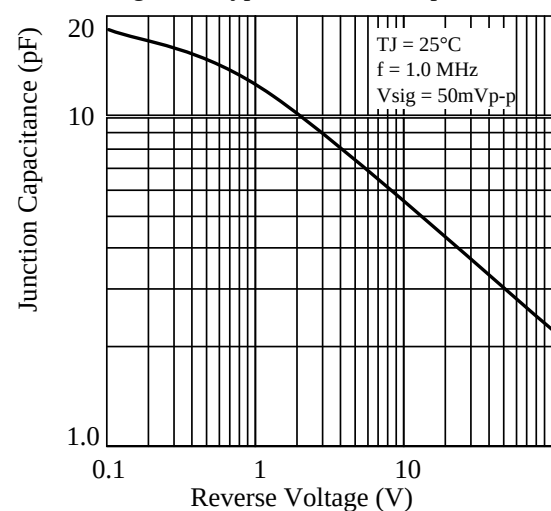
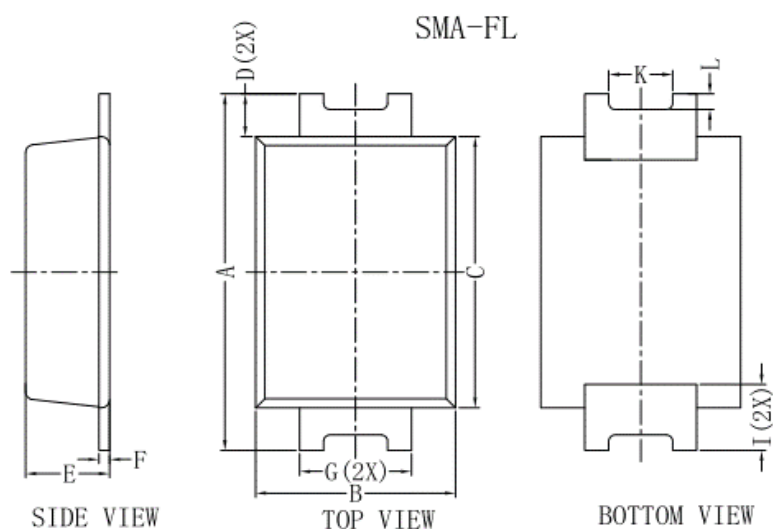


Fig 6. - Typical Junction Capacitance



6.OUTLINE AND DIMENSIONS

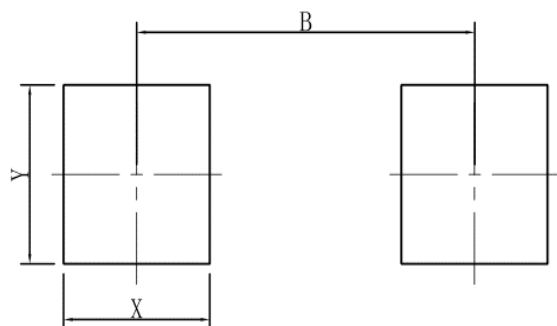


SMA-FL			
DIM	MIN	MAX	Typ.
A	4.40	4.80	4.60
B	2.30	2.70	2.60
C	3.30	3.70	3.50
D			0.55
E	0.90	1.20	1.05
F	0.11	0.21	0.17
G	1.30	1.50	1.40
I	-	-	0.90
K	-	-	0.80
L	-	-	0.20
All Dimensions in mm			

GENERAL NOTES

- 1.Top package surface finish $Ra0.4\pm0.2\mu m$
- 2.Bottom package surface finish $Ra0.7\pm0.2\mu m$

7.SOLDERING FOOTPRINT



SMA-FL	
DIM	(mm)
X	1.60
Y	1.80
B	3.70

单击下面可查看定价，库存，交付和生命周期等信息

[>>LRC\(乐山无线电\)](#)